

Product/process change notification

PCN213304

Dear

Please find attached our Infineon Technologies AG PCN:

Introduction of new substrate supplier and change of die attach material from DF-18C1 to EM760 for PBGA320 products at Amkor Technology Japan, Inc. Hakodate site

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **29 Sep 2021**
- Infineon aligns with the widely-recognized JEDEC STANDARD “**JESD46**“, which stipulates: **“Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.”**

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.



On 16 April 2020, Infineon acquired Cypress.
We are now in the process of merging and consolidating our tools and processes for PCN, Information Notes, Errata and Product Discontinuance.
For further details, please visit our website:
<https://www.infineon.com/cms/en/about-infineon/company/cypress-acquisition/>

► **Products affected:** Please refer to attached affected product list [7]

► **Detailed change information:**

Subject: Introduction of new substrate supplier and change of die attach material from DF-18C1 to EM760 for PBGA320 products assembled at Amkor Technology Japan, Inc. Hakodate site

Reason: Current substrate supplier will be EOL. There is no change of substrate design for the new substrate material by the new substrate supplier. To further improve/ensure our product performance the new die attach will be introduced

Description:	<u>Old</u>	<u>New</u>
	<ul style="list-style-type: none"> ■ Substrate supplier: DAISHO DENSHI CO., Ltd. 	<ul style="list-style-type: none"> ■ Substrate supplier: Korea Circuit Co., Ltd.
	<ul style="list-style-type: none"> ■ Die attach material: DF-18C1 	<ul style="list-style-type: none"> ■ Die attach material: EM760

► **Product identification:** Traceability of product to assembly site through the lot number marked on the package.

► **Impact of change:** Based on the qualification performed, Infineon does not see any negative impact on quality, function and reliability. No change in fit and form.

► **Attachments:** Affected product list [7]
Supporting documents

► **Time schedule:**

■ Final qualification report:	2021-07-30
■ First samples available:	on request
■ Intended start of delivery:	2022-01-31

If you have any questions, please do not hesitate to contact your local sales office.

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Introduction of new substrate supplier and change of die attach material from DF-18C1 to EM760 for select PBGA320 Auto MCU products



Item	Marketing Part Number	Family	Sample Order Part Number	Sample Availability
1	8945139744	Auto MCU	CY91F469GBP-B-GS-UJE1KR	on request
2	A2C00052707	Auto MCU	CY91F469QAHP-B-GS-UJE1KR	on request
3	A2C03111100	Auto MCU	MB91F469GBP-B-GS-K6E1KR	on request
4	CY91F469GBP-B-GS-UJE1	Auto MCU	CY91F469GBP-B-GS-UJE1KR	on request
5	CY91F469QAHP-B-GS-UJE1	Auto MCU	CY91F469QAHP-B-GS-UJE1KR	on request
6	MB91F469GBP-B-GS-K6E1	Auto MCU	MB91F469GBP-B-GS-K6E1KR	on request
7	MB91F469QAHP-B-GSK6E1	Auto MCU	MB91F469QAHP-B-GSK6E1KR	on request